Materials Declaration

Package	TQFP_EP
Body Size	7 x 7 x 1.0
LeadCount	48
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	88.00	6.98 E-02	513753
Biphenyl Resin	11.50	9.12 E-03	67137
Carbon black	0.50	3.97 E-04	2922

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.25	4.10 E-02	301810
Cr	0.30	1.24 E-04	913
Sn	0.25	1.03 E-04	758
Zn	0.20	8.30 E-05	611

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	5.60 E-04	4122

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	3.64 E-03	26800

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.26 E-03	9238

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	7.34 E-03	54042

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	1.70 E-03	12528
Resin	20.0	4.86 E-04	3577
Anhydride	10.0	2.43 E-04	1789

Molding Compound

Item	PPM	Method
Pb	None Detected	US EPA 3050B. ICP-AES
Cd	None Detected	EN 1122:2001. ICP-AES
Hg	None Detected	US EPA 3052. ICP - AES
Cr+6	None Detected	US EPA 3060A & 7196A.
PBB	None Detected	US EPA 3540C. Analysis performed by HPLC/DAD, LC/MS or GC/MS
PBDE	None Detected	US EPA 3540C. Analysis performed by HPLC/DAD, LC/MS or GC/MS

Die Attach Paste

Item	PPM	Method
Pb	None Detected	US EPA 3052. ICP -OES
Cd	None Detected	US EPA 3052. ICP -OES
Hg	None Detected	US EPA 3052. ICP -OES
Cr+6	None Detected	US EPA 3060A & 7196A . UV-VIS
PBB	None Detected	SGS-in house method. Analysis performed by GC/MS
PBDE	None Detected	SGS-in house method. Analysis performed by GC/MS

Package Totals

Weight (g)	PPM
1.36 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

Materials Declaration

Package	TQFP_EP
Body Size	7 x 7 x 1.0
LeadCount	48
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	88.00	6.98 E-02	512621
Biphenyl Resin	11.50	9.12 E-03	66989
Carbon black	0.50	3.97 E-04	2916

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.25	4.10 E-02	301145
Cr	0.30	1.24 E-04	911
Sn	0.25	1.03 E-04	756
Zn	0.20	8.30 E-05	610

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	5.60 E-04	4113

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.0	3.35 E-03	24604
Pb	15.0	5.91 E-04	4341

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.26 E-03	9217

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	7.34 E-03	53923

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	1.70 E-03	12500
Resin	20.0	4.86 E-04	3569
Anhydride	10.0	2.43 E-04	1785

Package Totals

Weight (g)	PPM
1.36 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	None Detected	US EPA 3050B. ICP-AES
Cd	None Detected	EN 1122:2001. ICP-AES
Hg	None Detected	US EPA 3052. ICP - AES
Cr+6	None Detected	US EPA 3060A & 7196A.
PBB	None Detected	US EPA 3540C. Analysis performed by HPLC/DAD, LC/MS or GC/MS
PBDE	None Detected	US EPA 3540C. Analysis performed by HPLC/DAD, LC/MS or GC/MS

Die Attach Paste

Item	PPM	Method
Pb	None Detected	US EPA 3052. ICP -OES
Cd	None Detected	US EPA 3052. ICP -OES
Hg	None Detected	US EPA 3052. ICP -OES
Cr+6	None Detected	US EPA 3060A & 7196A . UV-VIS
PBB	None Detected	SGS-in house method. Analysis performed by GC/MS
PBDE	None Detected	SGS-in house method. Analysis performed by GC/MS

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